

Gap Filler I100SF (Two-Part)

Thermally Conductive, Silicone-Free, Liquid Gap Filling Material

Features and Benefits

- Thermal conductivity: 1.1 W/m-K
- No silicone outgassing or extraction
- Ultra-conforming, designed for fragile and low-stress applications
- Ambient and accelerated cure schedules
- 100% solids – no cure by-products

Gap Filler I100SF is the thermal solution for silicone-sensitive applications. The material is supplied as a two-part component curing at room or elevated temperatures. The material exhibits “gel-like” properties then cures to a soft, flexible elastomer, helping reduce thermal cycling stresses during operation and virtually eliminating stress during assembly of low-stress applications.

The two components are colored to assist as a mix indicator (1:1 by volume). The mixed system will cure at ambient temperature. Unlike cured thermal pad materials, the liquid approach offers infinite thickness variations with little or no stress during assembly displacement. Gap Filler I100SF, although exhibiting some natural tack characteristics, is not intended for use in thermal interface applications requiring a mechanical structural bond.

Application

Gap Filler I100SF can be mixed and dispensed using dual-tube cartridge packs with static mixers and manual or pneumatic gun, or high volume mixing and dispensing equipment (application of heat may be used to reduce viscosity).

TEMPERATURE DEPENDENCE OF VISCOSITY

The viscosity of the Gap Filler I100SF material is temperature dependent. The table below provides the multiplication factor to obtain viscosity at various temperatures. To obtain the viscosity at a given temperature, look up the multiplication factor at that temperature and multiply the corresponding viscosity at 25°C.

| Temperature °C | Multiplication Factor | |
|-------------------|-----------------------|--------|
| | Part A | Part B |
| 20 | 1.43 | 1.57 |
| 25 | 1.00 | 1.00 |
| 35 | 0.58 | 0.50 |
| 45 | 0.39 | 0.30 |
| 50 | 0.32 | 0.24 |

Example - Viscosity of Part A @ 45°C:

Viscosity of Part A at 25°C is 450,000 cp. The multiplication factor for part A at 45°C is 0.39. Therefore:

$$(450,000) \times (0.39) = 175,500 \text{ cps}$$

TYPICAL PROPERTIES OF GAP FILLER I100SF

| PROPERTY | IMPERIAL VALUE | METRIC VALUE | TEST METHOD |
|---------------------------------|------------------|------------------|-------------|
| Color / Part A | Yellow | Yellow | Visual |
| Color / Part B | Red | Red | Visual |
| Viscosity as Mixed (cps) (1) | 450,000 | 450,000 | ASTM D2196 |
| Density (g/cc) | 2.0 | 2.0 | ASTM D792 |
| Mix Ratio | 1:1 | 1:1 | — |
| Shelf Life @ 25°C (months) | 6 | 6 | — |
| PROPERTY AS CURED | | | |
| Color | Orange | Orange | Visual |
| Hardness (Shore 00) (2) | 60 | 60 | ASTM D2240 |
| Heat Capacity (J/g-K) | 0.9 | 0.9 | ASTM E1269 |
| Continuous Use Temp (°F) / (°C) | -76 to 257 | -60 to 125 | — |
| ELECTRICAL AS CURED | | | |
| Dielectric Strength (V/mil) | 400 | 400 | ASTM D149 |
| Dielectric Constant (1000 Hz) | 5.0 | 5.0 | ASTM D150 |
| Volume Resistivity (Ohm-meter) | 10 ¹⁰ | 10 ¹⁰ | ASTM D257 |
| Flame Rating | V-O | V-O | U.L. 94 |
| THERMAL AS CURED | | | |
| Thermal Conductivity (W/m-K) | 1.1 | 1.1 | ASTM D5470 |
| CURE SCHEDULE | | | |
| Pot Life @ 25°C (min) (3) | 10-15 | 10-15 | — |
| Cure @ 25°C (hrs) (4) | 4 | 4 | — |
| Cure @ 100°C (min) (4) | 45 | 45 | — |

- 1) Brookfield RV, Heli-Path, Spindle TF @ 2 rpm, 25°C.
- 2) Thirty second delay value Shore 00 hardness scale.
- 3) Time for viscosity to double.
- 4) Cure schedule (rheometer - time to read 90% cure)

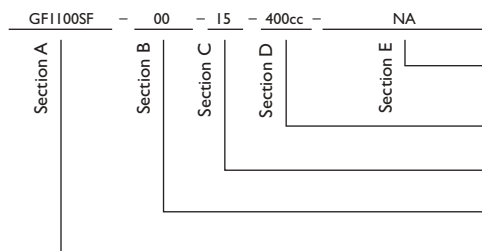
Typical Applications Include:

- Silicone-sensitive optic components
- Silicone-sensitive electronics
- Filling various gaps between heat-generating devices to heat sinks and housings
- Mechanical switching relay
- Hard disk assemblies
- Dielectric for bare-leaded devices

Configurations Available:

- Supplied in cartridge or kit form

Building a Part Number



Standard Options

« example

NA = Selected standard option. If not selecting a standard option, insert company name, drawing number, and revision level.

Cartridges: 400cc = 400.0cc
Kits: 1200cc = 1200.0cc, or 10G = 10 gallon

Pot Life: 15 = 15 minutes

00 = No spacer beads
07 = 0.007" spacer beads

GF I100SF = Gap Filler I100SF Material

Note: To build a part number, visit our website at www.bergquistcompany.com.

Gap Pad®: U.S. Patent 5,679,457 and others.



www.bergquistcompany.com

The Bergquist Company -
North American Headquarters
18930 West 78th Street
Chanhassen, MN 55317
Phone: 800-347-4572
Fax: 952-835-0430

The Bergquist Company - Europe
Bramenberg 9a, 3755 BT Eemnes
Netherlands
Phone: 31-35-5380684
Fax: 31-35-5380295

The Bergquist Company - China
Rm. 7C, Aih Mansion
No. 629 Ling Ling Road
Shanghai, China 200030
Ph: 86-21-6464-2206
Fax: 86-21-6464-2209

All statements, technical information and recommendations herein are based on tests we believe to be reliable, and THE FOLLOWING IS MADE IN LIEU OF ALL WARRANTIES, EXPRESSED OR IMPLIED, INCLUDING THE IMPLIED WARRANTIES OF MARKETABILITY AND FITNESS FOR PURPOSE. Sellers' and manufacturers' only obligation shall be to replace such quantity of the product proved to be defective. Before using, user shall determine the suitability of the product for its intended use, and the user assumes all risks and liability whatsoever in connection therewith. NEITHER SELLER NOR MANUFACTURER SHALL BE LIABLE EITHER IN TORT OR IN CONTRACT FOR ANY LOSS OR DAMAGE, DIRECT, INCIDENTAL OR CONSEQUENTIAL, INCLUDING LOSS OF PROFITS OR REVENUE ARISING OUT OF THE USE OR THE INABILITY TO USE A PRODUCT. No statement, purchase order or recommendations by seller or purchaser not contained herein shall have any force or effect unless in an agreement signed by the officers of the seller and manufacturer.
PDS_10057_SP_1500ST_1204